

MILD-PLASMA™ × Adhesive-Free Bonding

Ultra-Low-Loss CCL Manufacturing Process for 5G/6G Applications

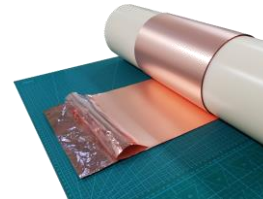
- Maximize high-frequency performance with smooth, direct bonding of fluoropolymer and smooth copper foil
- Maximize productivity with a roll-to-roll manufacturing process

MILD-PLASMA™
(Pre-treatment)

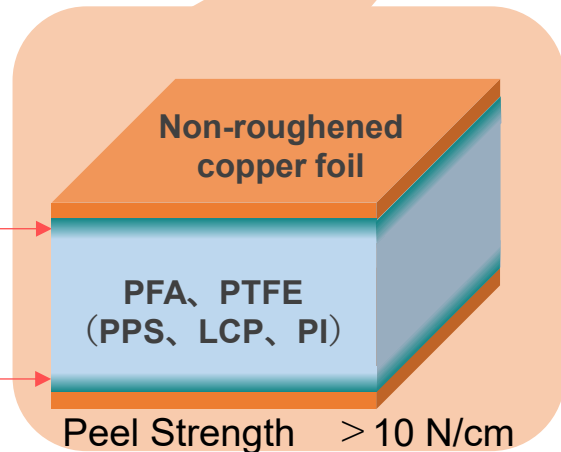


Complete the entire process with roll-to-roll manufacturing

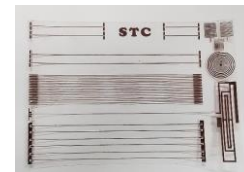
CCL
(Roll Lamination Bonding)



MILD-PLASMA™
Treatment



Etching
(Circuit Formation)

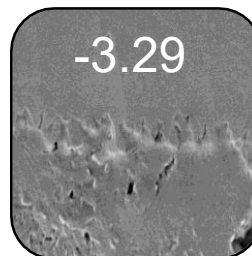


Substrate Processing



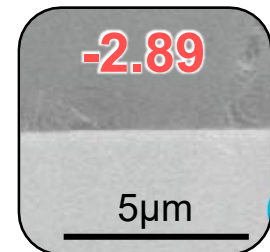
Transmission Loss
(dB/100mm@80GHz)

Conventional



Mechanical anchoring

MILD-PLASMA™



No Adhesive
No mechanical anchoring
*Microstrip line measurement



Download Brochure

STC

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<https://www.stc-jp.co.jp/>